



SLOVENSKI STANDARD
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Polprevodniški elementi - Preskusne metode zanesljivosti za vibracijske energetske zbiralnike - 1. del: Mehanska zanesljivost pri udarcih

Semiconductor devices - Reliability test methods for vibration energy harvesters - Part 1: Mechanical reliability under shock

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47/3000/CDV

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TITLE:

Semiconductor devices - Reliability test methods for vibration energy harvesters - Part 1: Mechanical reliability under shock

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES

– RELIABILITY TEST METHODS FOR VIBRATION ENERGY HARVESTERS –
Part 1: Mechanical Reliability Under Shock

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Draft	Report on voting
XX/XX/FDIS	XX/XX/RVD

114
115 Full information on the voting for its approval can be found in the report on voting indicated in
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117 The language used for the development of this International Standard is English.

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